

07/06/01
U.S. PTO
JC979 U.S. PTO
09/06/01

099000054-070601

07-09-01

A

PATENT

Docket No. JCLA6831

Date: 7-6-2001

JC979 U.S. PTO
09/06/01

Page 1

ASSISTANT COMMISSIONER FOR PATENTS

WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sir:

Transmitted herewith for filing is the patent application of

Inventors: Yi-Chuan Ding, In-De Ou, Kun-Ching Chen, Yung-I Yeh

For: FLIP CHIP PROCESS

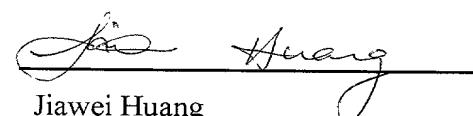
Enclosed are:

- Specification 12 pages.
- 4 Sheets of drawings
- Recordation Form Cover sheet with 2 pages assignment.
- A certified copy of Taiwan Patent Application No. dated
- SIGNED** declaration and power of attorney.
- Return Prepaid postcard.

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$710.00	\$710.00
Total Claims	12	— 20 = 0	× \$18.00	\$0.00
Independent Claims	2	— 3 = 0	× \$80.00	\$0.00
If application contains any multiple dependent claim(s), then add			\$270.00	\$0.00
TOTAL FILING FEE				\$710.00

- A check in the amount of \$710.00 cover the filing fee is enclosed.
- A check in the amount of \$40.00 to cover the assignment recording fee.
- A duplicate copy of this sheet is enclosed.


Jiawei Huang

Registration No. 43,330

J.C. PATENTS, INC.
1340 REYNOLDS AVE., SUITE 114
IRVINE, CALIFORNIA 92614
(949) 660-0761
FAX: (949) 660-0809

Assistant Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No. : JCLA6831
Applicant(s) : Yi-Chuan Ding, In-De Ou, Kun-Ching Chen,
For Yung-I Yeh
"Express Mail" : EL 800897430 US
Mailing Label No.
Date of Deposit : *July 6, 2001*

I hereby certify that the accompanying

Transmittal in Duplicate; Specification 12 pages, 4 sheets of drawings; **SIGNED**
Declaration and Power of Attorney 2 pages; Recordation Form Cover Sheet and
Assignment 3 pages; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to
Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the
Assistant Commissioner for Patents, Washington, D.C. 20231.

m. chang
Michelle Chang